

Summary Of mpw2Sldo Test Irradiations

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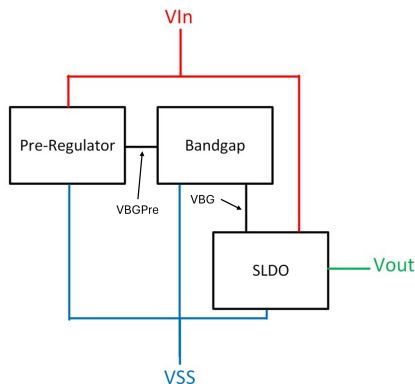
Content:

- 040mA Load Irradiations and Annealing
- 500mA Load Irradiations and Annealing
- 900mA Load Irradiations and Annealing

Overview

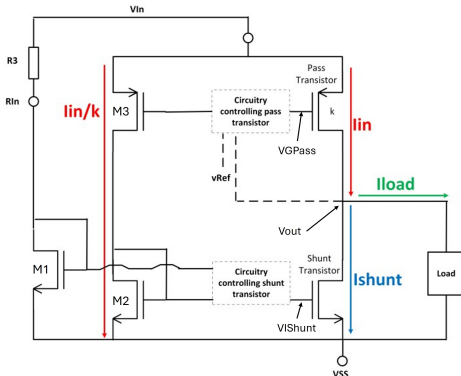
- SLDO Circuit
- Setup
- Test Plan
- Results of Irradiation and Annealing
- Conclusion

SLDO Chip



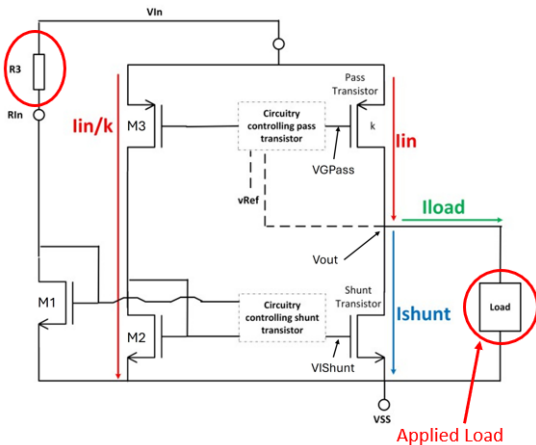
- Made of three main blocks.
- 1st block is a pre-regulator that delivers a clean supply to the main bandgap (2nd block), which provides a reference voltage for the SLDO.
- The 3rd block is the actual SLDO circuit.

SLDO Circuit



- Pass Transistor and its control circuitry form a traditional LDO that regulates the output voltage (V_{out}) to v_{Ref} .
- Shunt Transistor provides an additional path to shunt excess current (I_{shunt}).
- $R3$ sets the reference current that is used in combination with I_{in}/k to regulate the Shunt Transistor (V_{Ishunt}).

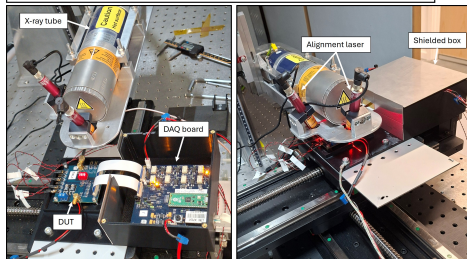
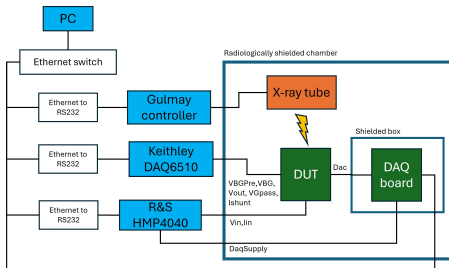
SLDO Operation Modes



- Operates at 40mA, 500mA or 900mA.
- Device operating range is set via the DAQ board.
- Sets the applied load and rheostat R3.

Test Setup

- Measuring:
Vin, In, VBGPre, VBG, Vout, VGpass, Ishunt and Temperature.
- Expected TID over 10 year lifetime is $\sim 200\text{krad}(\text{SiO}_2)$. The devices were irradiated up to $\times 100$ the expected TID.
- Measurements were performed before, during and after irradiation.
- Distance from X-ray tube to DUT: 33.3mm.
- Two Dose rates: Standard and Low.
(Calibrated with CERN-EP-ESE group's procedure).
- Standard dose rate : $104\text{ krad}(\text{SiO}_2)/\text{min}$.
irradiation step: $\sim 204\text{ krad}(\text{SiO}_2)$.
(i.e. irradiate for 2 mins at $\sim 104\text{ krad}(\text{SiO}_2)/\text{min}$).
X-ray tube settings: 20kV, 20mA
- Low dose rate : $\sim 20.8\text{ krad}(\text{SiO}_2)/\text{min}$
irradiation step: $\sim 60\text{ krad}(\text{SiO}_2)$.
(i.e. irradiate for 3 mins at $\sim 20.8\text{ krad}(\text{SiO}_2)/\text{min}$).
X-ray tube settings: 20kV, 4mA
- Data taking automated via python scripts.

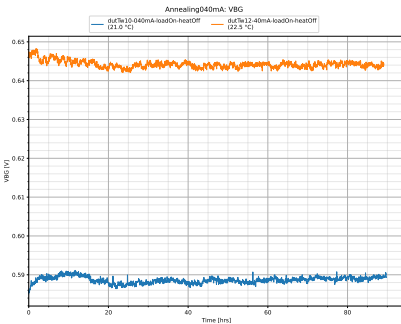
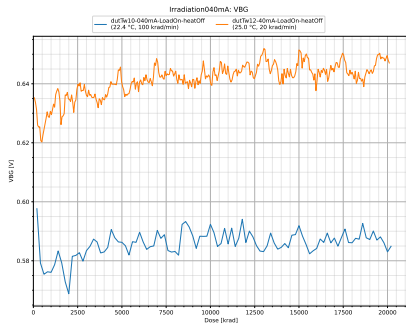
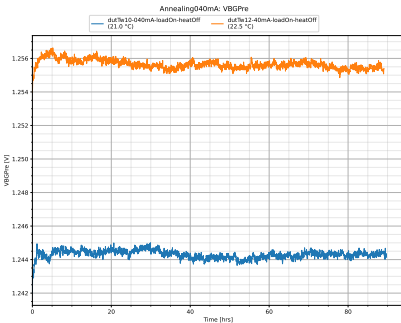
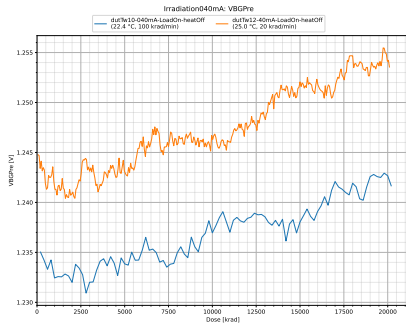


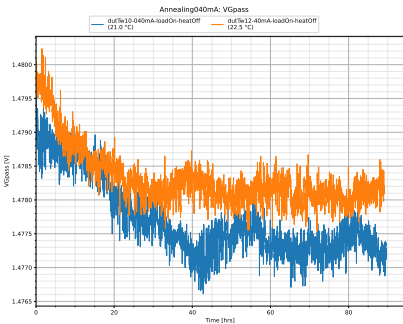
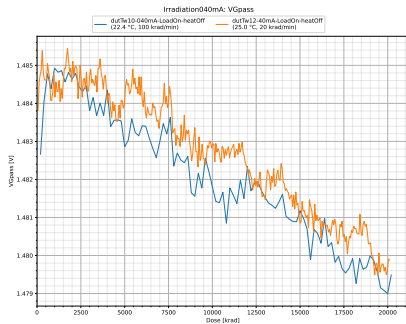
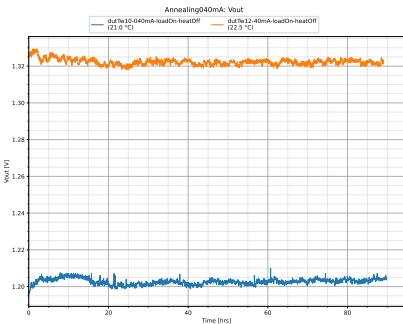
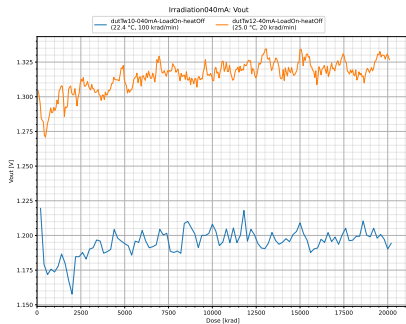
Irradiation Test Plan

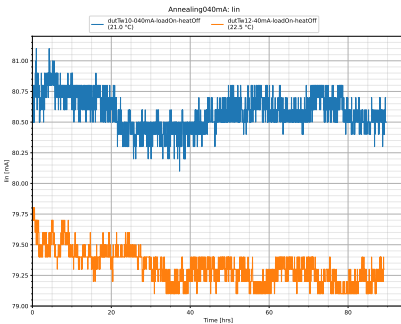
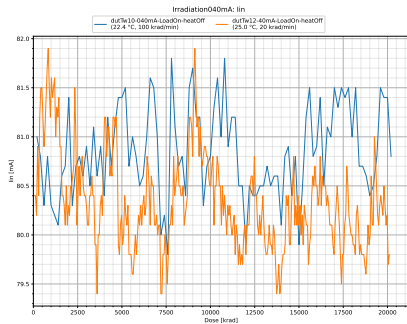
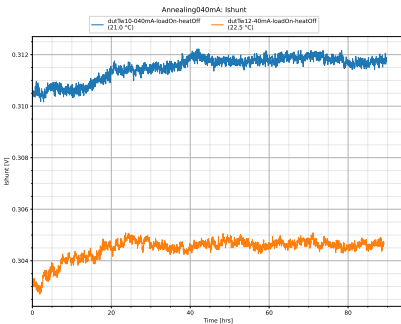
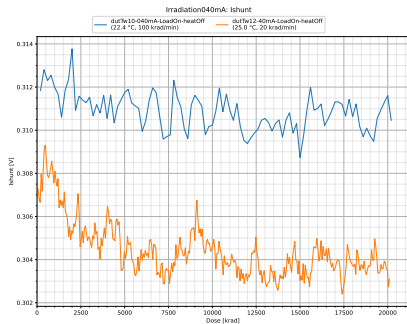
#	Dose range	Dose rate	To measure	Conditions	Annealing	DUT
1	0 - 10 Mrad Step of 200krad (i.e. 1 point every 2 mins)	100krad/min 20kV;20mA;	Vin, Iin; Vout (steady&DAC scan); VG PASS; VBG; VBGpre; Ishunt (is a Voltage); Temp;	Room-T (i.e. heaters off) (Irrad@DAC const@16 DN) (Load ON)	Keep monitoring every 2 mins for up to 5 days (i.e. 3600 pts)	-DutTw1, 500mA [under biased] ; Done;
2	0 - 20 Mrad Step of 200krad (i.e. 1 point every 2 mins)	100krad/min 20kV;20mA;	Vin, Iin; Vout (steady&DAC scan); VG PASS; VBG; Ishunt (is a Voltage); Temp;	Room-T (i.e. heaters off) (Irrad@DAC const@16 DN) (Load ON)	Keep monitoring every 2 mins for up to 5 days (i.e. 3600 pts)	-DutTw4, 500mA [under biased] ; Done; -DutTw5,500mA; Done; -DutTw6,900mA; Done; -DutTw10,40mA; Done;
3	0 - 20Mrad Step of 60krad (i.e. 1 point every 3 mins) (*16hrs total <u>irrad</u> time)	20krad/min 20kV;4mA;	Vin, Iin; Vout (steady&DAC scan); VG PASS; VBG; VBGpre; Ishunt (is a Voltage); Temp;	Room-T (i.e. heaters off) (Irrad@DAC const@16 DN) (Load ON)	Keep monitoring every 2 mins for up to 5 days (i.e. 3600 pts)	-DutTw11,500mA;Done -DutTw9,900mA;Done; -DutTw12,40mA;Done;
4	0 - 20Mrad Step of 60krad (i.e. 1 point every 3 mins) (*16 hrs total <u>irrad</u> time)	20krad/min 20kV;4mA;	Vin, Iin; Vout (steady&DAC scan); VG PASS; VBG; VBGpre; Ishunt (is a Voltage); Temp;	+60C (i.e. heaters on) (Irrad@DAC const@16 DN) (Load ON or OFF, mixed)	Keep monitoring every 2 mins for up to 5 days (i.e. 3600 pts)	-DutTw13, 500mA; [w Load off only during irrads] ; Done; -DutTw19, 500mA; LoadOn; Done; -DutTw20, 500mA; LoadOff; Done; -DutTw8, 900mA; LoadOn; Done; -DutTw15, 900mA; LoadOff; [lin FUSE triggered during Irradiation] ; Done; -DutTw16, 900mA; LoadOff; [lin FUSE triggered during Annealing] ; Done;
5	0 - 20Mrad Step of 60krad (i.e. 1 point every 2 mins) (*16hrs total <u>irrad</u> time)	20krad/min 20kV;4mA;	Vin, Iin; Vout (steady&DAC scan); VG PASS; VBG; VBGpre; Ishunt (is a Voltage); Temp;	Room-T (i.e. heaters off) (Irrad@DAC const@16 DN) (Load OFF)	Keep monitoring every 2 mins for up to 5 days (i.e. 3600 pts)	-DutTw17, 500mA; Done; -DutTw18, 900mA; Done;

40 mA Load Region Irradiation and Annealing

Device	Load	Heat	Vin [V]	Dose Rate [krad/min]	Comments
Tw10	On	Off	1.80	104	-
Tw12	On	Off	1.80	20	-



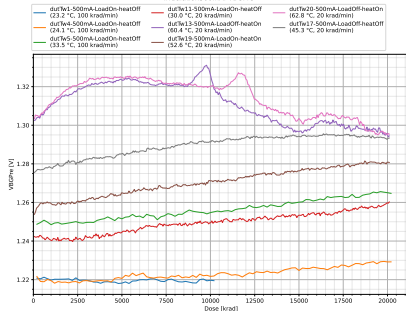




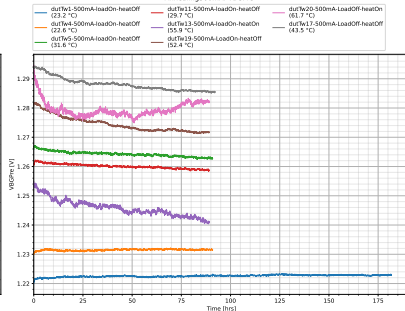
500mA Load Region Irradiation and Annealing

Device	Load	Heat	Vin [V]	Dose Rate [krad/min]	Comments
Tw1	On	Off	~1.55	104	- Underbiased due to Vin sense not enabled.
Tw4	On	Off	~1.55	104	- Underbiased due to Vin sense not enabled.
Tw5	On	Off	1.80	104	-
Tw11	On	Off	1.80	20	-
Tw13	Off/On	Off	1.80	20	- Load Off during Irradiation. Turned On for Annealing.
Tw19	On	On	1.80	20	-
Tw20	Off	On	1.80	20	- ~4 hrs gap between irradiation and annealing. DUT was powered OFF, with the heat kept ON during this time.
Tw17	Off	Off	1.80	20	-

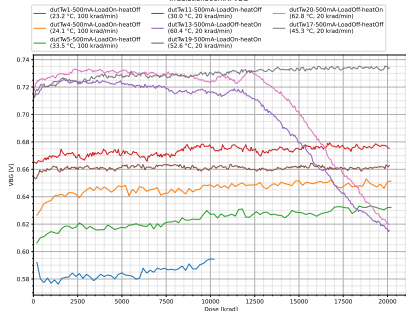
Irradiation500mA: VBGPre



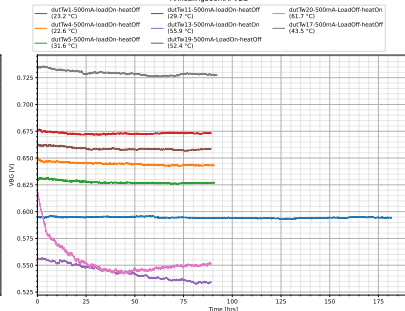
Annealing500mA: VBGPre

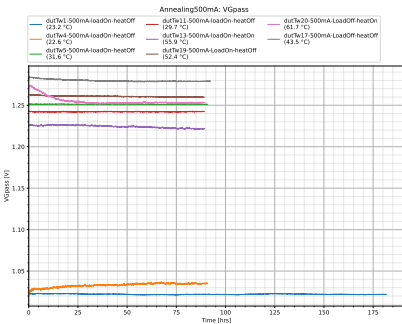
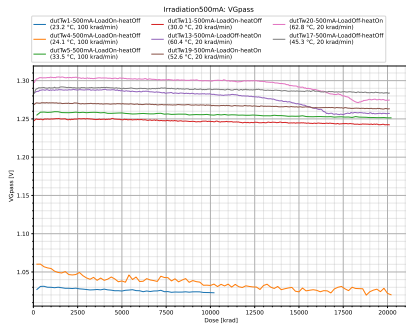
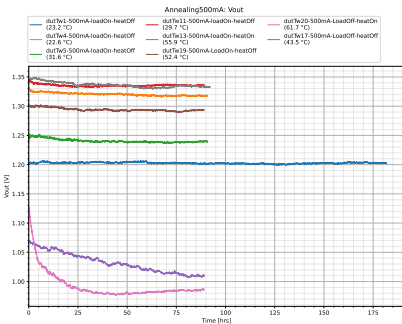
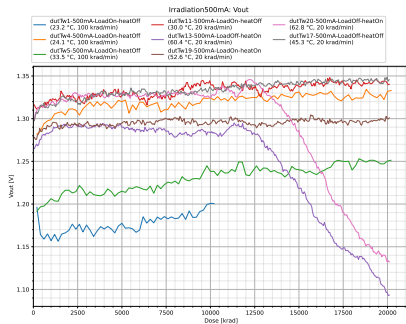


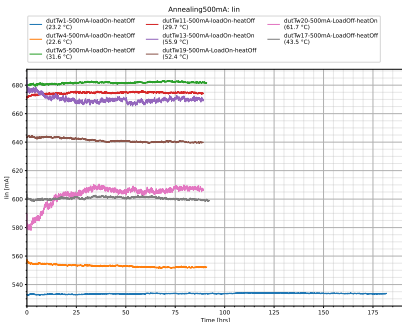
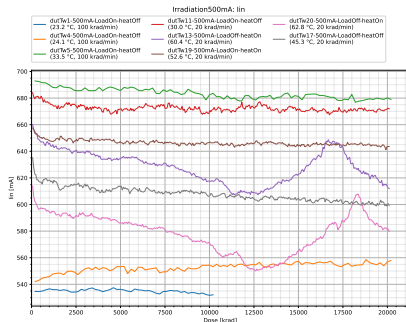
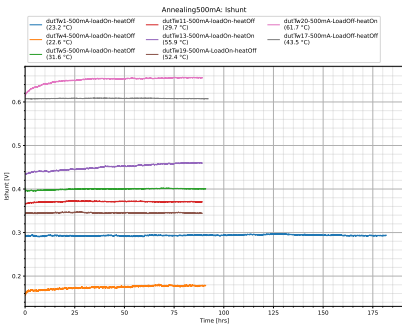
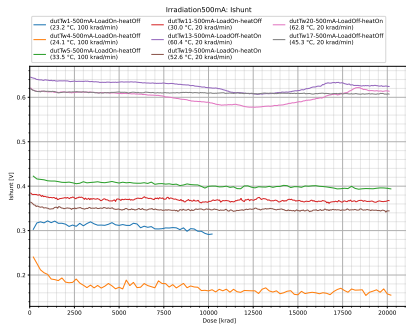
Irradiation500mA: VBG



Annealing500mA: VBG

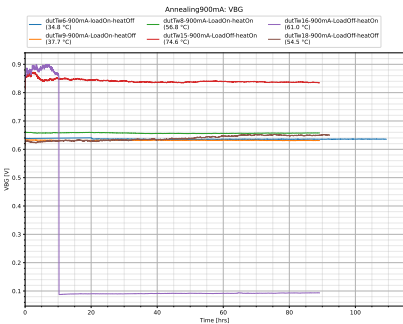
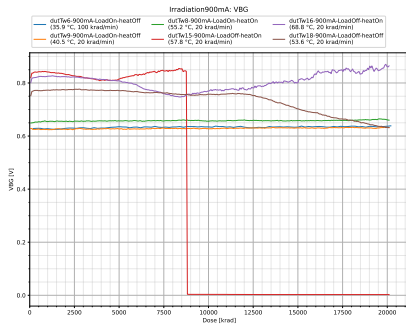
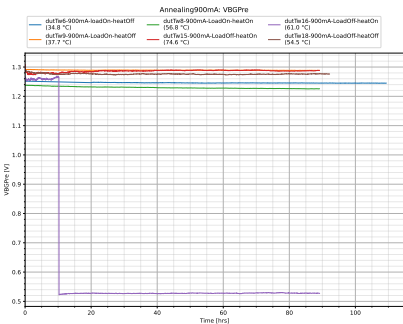
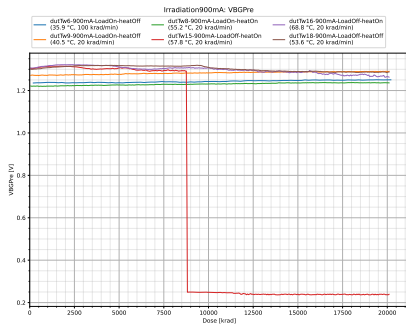


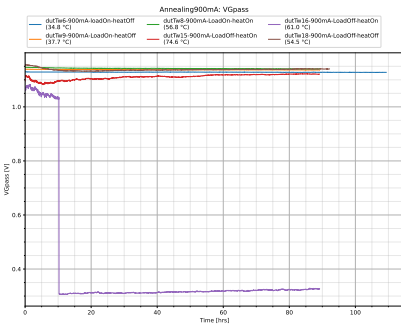
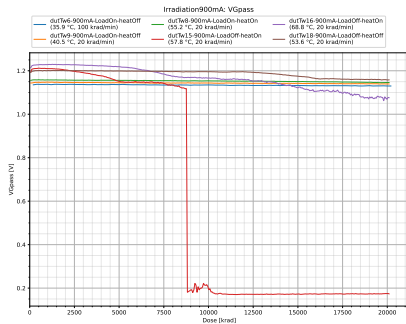
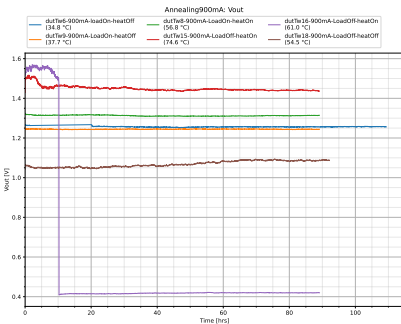
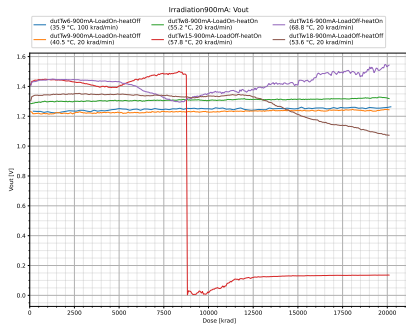


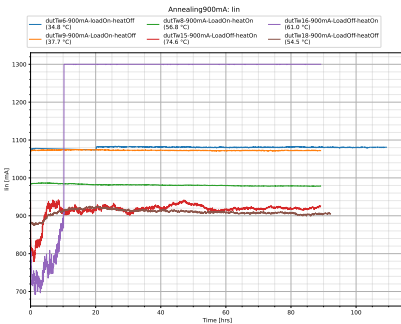
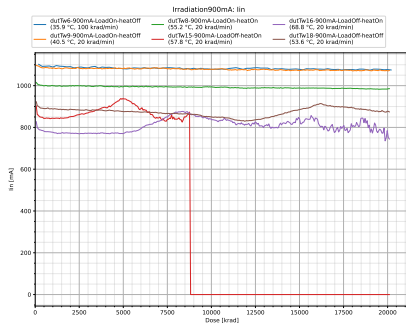
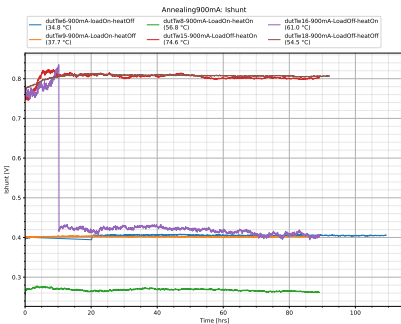
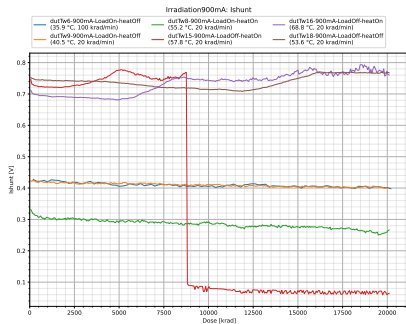


900 mA Load Region Irradiation and Annealing

Device	Load	Heat	Vin [V]	Dose Rate [krad/min]	Comments
Tw6	On	Off	1.80	104	- During post-irrad annealing, data was lost from 1.5 - ~20hrs
Tw9	On	Off	1.80	20	-
Tw8	On	On	1.80	20	-
Tw15	Off	On	1.80	20	- ~9Mrad during irradiation: lin hit compliance, switching off PSU. Vout is not at 0V because the communication pins are enabled, and signals lift the sensor from GND. Post irrad, DUT powers up w/o short.
Tw16	Off	On	1.80	20	- During Annealing lin fuse triggered Vin~0.7 instead of 1.8
Tw18	Off	Off	1.80	20	-







Conclusion

- 16 SLDO-chips were irradiated up to 20Mrad(SiO_2) (i.e. x100 more TID than required by SVT 200krad(SiO_2)).
- V_{in} , I_{in} , V_{out} , V_{Gpass} , V_{BG} , I_{shunt} , V_{BGPre} and Temperature were measured at regular intervals during irradiation and annealing.
- DUTs show a higher sensitivity to TID when the load was OFF and when heat was ON.